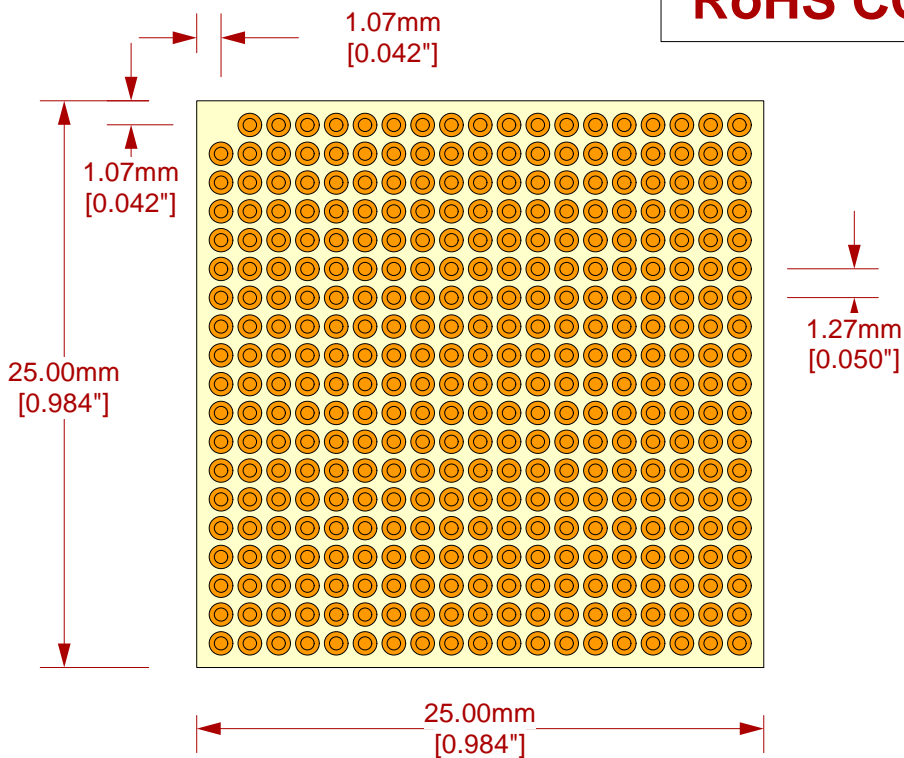
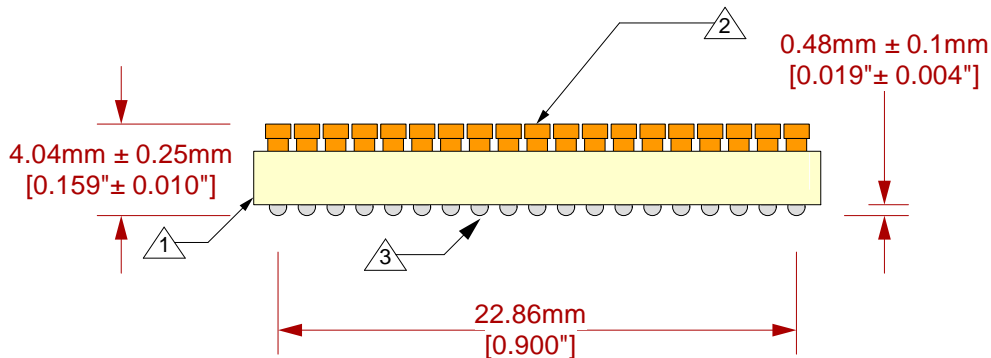


Top View

RoHS COMPLIANT



Side View




- △1 Substrate: 2.39mm ±0.18mm [0.094" ±0.007"]
FR4/G10 or equivalent high temp material.
17µm [1/2 oz.] (RoHS)
- △2 Pins: shell material- Brass Alloy 360 1/2 hard;
finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni
(min.). Contact material- BeCu; finish 0.25µm
[10µ"] Au over 1.27µm [50µ"] Ni (min.).
- △3 Solder balls: Sn96.5 Ag3.0 Cu0.5

Description: Giga-snaP BGA SMT Foot

360 position (1.27mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SF-BGA360A-B-72F Drawing	Status: Released	Scale: 4:1	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 03/22/07
		File: SF-BGA360A-B-72F Dwg	Modified:	